



# **Product Specifications July 1997**(1 of 4)

## **Features**

- ☐ High Gain
- ☐ +30 dBm Power Output
- **☐** Proprietary Power FET Process
- □ >40% Linear Power Added Efficiency
- ☐ Surface Mount SO-8 Power Package

## **Applications**

- ☐ ISM Band Base Stations and Terminals
- ☐ RF ID/POS Base Stations
- **☐** Wireless Local Loop

## **Description**

The CFK2062-P5 is a high-gain FET intended for driver amplifier applications in high-power systems, and output stage usage in medium power applications at power levels up to +30 dBm. The device is easily matched and provides excellent

**Specifications** (TA =  $25^{\circ}$ C) The following specifications are guaranteed at room temperature in Celeritek test fixture at 2.45 GHz.

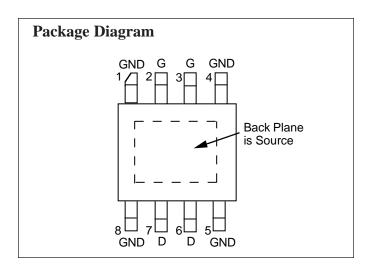
Parameters	Conditions	Min	Тур	Max	Units
$V_d = 8V, I_d =$	400 mA (Quiescent)				
P <sub>-1dB</sub>		30.0	31.0	_	dBm
SSG		12.0	13.0	_	dB
3rd Order Products (1)		_	30	_	dBc
Efficiency	@ P1dB		40	_	%
$\overline{\mathbf{V_d} = 5\mathbf{V}, \mathbf{I_d}} =$	= 600 mA (Quiescent)				
P <sub>-1dB</sub>		_	30.5	_	dBm
SSG			12.0	_	dB

Parameters	Conditions	Min	Тур	Max	Units
g <sub>m</sub>	Vds = 2.0V, Vgs = 0V	_	650	_	mS
$\overline{I_{dss}}$	Vds = 2.0V, Vgs = 0V	_	1.4	_	A
$\overline{ m V_p}$	Vds = 3.0V, $Ids = 25  mA$	_	-1.8		Volts
BV <sub>GD</sub>	Igd = 2.5  mA	15	17	_	Volts
$\Theta_{JL}$ (2)	@150°C TCH	_	12	_	°C/W

### **Absolute Maximum Ratings**

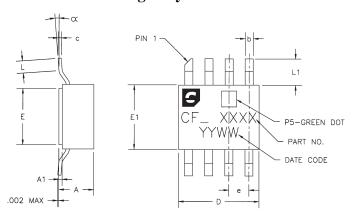
Parameter	Symbol	Rating
Drain-Source Voltage	$v_{DS}$	10V (3)
Gate-Source Voltage	$v_{GS}$	-5V
Drain Current	$I_{DS}$	Idss
Continuous Dissipation	$P_{T}$	6W
Channel Temperature	$T_{CH}$	175°C
Storage Temperature	$T_{STG}$	$-65^{\circ}$ C to $+175^{\circ}$ C

## 2.3 to 2.5 GHz +30 dBm Power GaAs FET



linearity at 1 Watt. Manufactured in Celeritek's proprietary power FET process, this device is assembled in an industry standard surface mount SO-8 power package that is compatible with high volume, automated board assembly techniques.

## **SO-8 Power Package Physical Dimensions**



DIMENSION	MINIMUM	NOMINAL	MAXIMUM
А		.086[2.184]	.100[2.540]
A1	.005[.1270]	.008[.2032]	.011[.2794]
b	.017[.4318]	.020[.5080]	.023[.5842]
C-	.007[.1778]	.008[2032]	.009[.2286]
D	.195[4.953]	.200[5.080]	.205[5.207]
E	.135[3.429]	.140[3.556]	.145[3.683]
E1	.155[3.937]	.160[4.064]	.165[4.191]
е		.050[1.270]	
L	.020[.5080]		.040[1.016]
L1	.055[1.397]	.065[1.651]	.075[1.905]
α	0,		8.

DIMENSIONS IN INCHES [MILIMETERS]

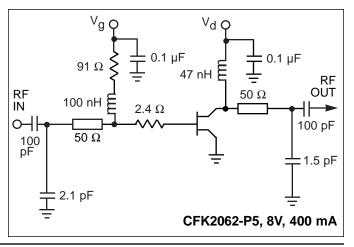
Phone: (408) 986-5060

#### Notes:

- 1. Sum to two tones with 1 MHz spacing = 25 dBm.
- 2. See thermal considerations information on page 4.
- 3. Maximum potential difference across the device (Vd + Vg) cannot exceed 12V.

Typical Scattering Parameters		$(TA = 25^{\circ}C, Vds = 5 V, Ids = 600 mA)$							
Frequency S		S <sub>11</sub>	s <sub>21</sub>		S <sub>1</sub>	S <sub>12</sub>		S <sub>22</sub>	
(GHz)	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang	
0.6	0.927	-129.75	8.7	102.7	0.024	21.95	0.576	-178.45	
1.0	0.914	-154.69	5.449	84.82	0.025	8.72	0.6	175.04	
1.8	0.889	-174.42	3.768	61.32	0.033	-5.24	0.53	163.11	
1.9	0.866	-178.39	3.693	57.12	0.035	-8.52	0.52	159.17	
2.0	0.883	177.09	3.605	52.62	0.05	-10.6	0.512	154.61	
2.1	0.78	171.92	3.504	48.01	0.035	-14.75	0.508	149.35	
2.2	0.879	166.48	3.386	42.82	0.036	-18.18	0.509	143.77	
2.3	0.88	160.6	3.243	37.96	0.036	-22.89	0.515	137.96	
2.4	0.884	154.86	3.09	32.93	0.035	-26.59	0.528	132.84	
2.5	0.887	150.54	2.944	28.96	0.035	-30.13	0.539	128.94	
2.6	0.891	145.9	2.757	24.85	0.035	-32.91	0.555	124.99	
2.7	0.899	141.82	2.57	20.93	0.035	-37.19	0.574	122.00	
3.0	0.917	135.01	2.081	13.19	0.03	-41.27	0.623	118.42	
3.5	0.932	137.14	1.635	8.18	0.028	-41.69	0.643	124.18	
4.0	0.913	143.42	1.641	3.36	0.032	-41.15	0.557	131.38	
			(TA = 25	$S^{\circ}C$ , $Vds = 8 V$ ,	Ids = 400  mA)				
0.6	0.91	-131.25	9.129	100.5	0.026	17.07	0.521	-174.04	
1.0	0.904	-155.33	5.68	82.61	0.027	6.34	0.548	178.8	
1.8	0.883	-174.77	3.86	58.87	0.034	-7.72	0.483	168.5	
1.9	0.88	-178.6	3.783	54.83	0.034	-9.68	0.472	164.9	
2.0	0.877	176.74	3.696	50.36	0.035	-13.77	0.463	160.21	
2.1	0.873	171.86	3.589	45.5	0.036	-16.17	0.458	154.9	
2.2	0.874	166.29	3.46	40.56	0.037	-21.9	0.458	149.35	
2.3	0.876	160.6	3.324	35.55	0.036	-26.41	0.463	143.16	
2.4	0.878	154.94	3.159	30.56	0.036	-29.59	0.475	137.57	
2.5	0.882	150.43	3.014	26.66	0.036	-31.65	0.486	133.49	
2.6	0.888	145.65	2.872	22.43	0.035	-33.01	0.504	129.21	
2.7	0.893	141.74	2.643	18.41	0.035	-39.11	0.524	125.87	
3.0	0.915	135.06	2.136	10.26	0.031	-46.6	0.579	121.99	
3.5	0.93	137.37	1.662	4.59	0.027	-43.86	0.611	128.44	
4.0	0.912	143.75	1.642	-0.35	0.031	-43.95	0.541	137.64	

 $RF\ Match\$  Data shown in the performance graphs was taken in the test circuit shown at right. Layout is important for proper operation. Phase length of input and output  $50\Omega$  line varies as a function of exact desired frequency of operation. Output shunt inductor effects output performance. Celeritek recommends the use of a high impedance printed inductor Lambda/4 in length. Please contact the factory for an evaluation board and/or more detailed application support.







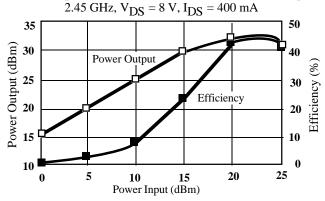


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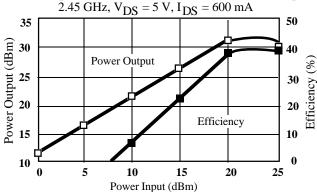
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## **Typical Performance**

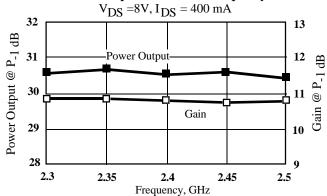
Power Output & Power Added Efficiency vs Power Input



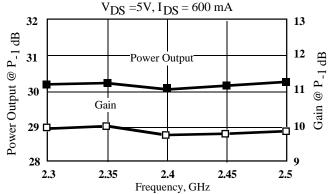
Power Output & Power Added Efficiency vs Power Input



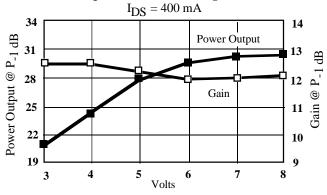
**Power Output and Gain vs Frequency** 



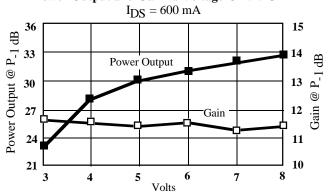
**Power Output and Gain vs Frequency** 



## Power Output and Gain vs Voltage @ 2.45 GHz



Power Output and Gain vs Voltage @ 2.45 GHz

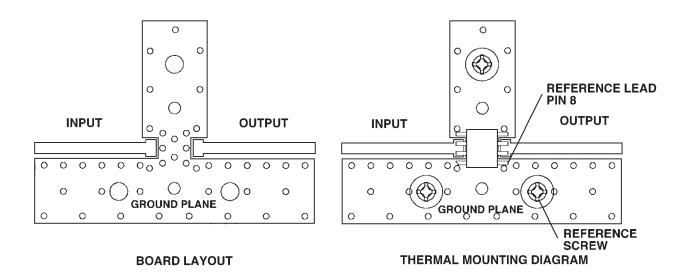


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#### **Thermal Considerations**

The data shown was taken on a 31 mil thick FR-4 board with 1 ounce copper on both sides. The board was mounted to a base-plate with 3 screws as shown. The screws bring the top side copper temperature to the same value as the baseplate. The thermal resistance to the indicated reference lead,  $\Theta_{II}$ , is 12°C/W. The thermal resistance to the reference screw is 14°C/W.

- 1. Use 1 or 2 ounce copper if possible.
- 2. Solder all eight leads of the CFK2062-P5 package to the appropriate electrical connection.
- 3. Solder the copper pad on the backside of the CFK2062-P5 package to the ground plane.
- 4. Use a large ground pad area with many plated through-holes as shown.
- 5. If possible, use at least one screw no more than 0.2 inches from the CFK2062-P5 package to provide a low thermal resistance path to the baseplate of the package.



## **Ordering Information**

The CFK2062-P5 power stage is available in a SO-8 surface mount package. Devices are available in tape and reel. Ordering part numbers are listed.

Part Number for Ordering Function Package

CFK2062-P5 2.3 - 2.5 GHz Power Stage SO-8 surface mount power package

CFK2062-P5-000T 2.3 - 2.5 GHz Power Stage SO-8 surface mount power package in tape and reel

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